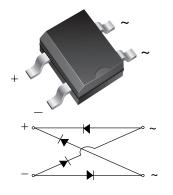
# RMB2S & RMB4S

Vishay General Semiconductor

# Miniature Glass Passivated Fast Recovery Surface Mount Bridge Rectifier



TO-269AA (MBS)

PRIMARY CHARACTERISTICS				
I <sub>F(AV)</sub>	0.5 A			
V <sub>RRM</sub>	200 V, 400 V			
I <sub>FSM</sub>	30 A			
t <sub>rr</sub>	150 ns			
V <sub>F</sub>	1.25 V			
T <sub>J</sub> max.	150 °C			

### FEATURES

- UL recognition, file number E54214
- Saves space on printed circuit boards
- · Ideal for automated placement
- Fast recovery, low switching loss
- High surge current capability
- Meets MSL level 1, per J-STD-020, LF maximum peak of 250 °C
- Solder dip 260 °C, 40 s
- Component in accordance to RoHS 2002/95/EC and WEEE 2002/96/EC

### **TYPICAL APPLICATIONS**

General purpose use in ac-to-dc bridge full wave rectification for power supply, lighting ballaster, battery charger, home appliances, office equipment, and telecommunication applications.

### **MECHANICAL DATA**

Case: TO-269AA (MBS)

Epoxy meets UL 94V-0 flammability rating

**Terminals:** Matte tin plated leads, solderable per J-STD-002 and JESD22-B102

E3 suffix for commercial grade, meets JESD 201 class 1A whisker test

Polarity: As marked on body

MAXIMUM RATINGS (T <sub>A</sub> = 25 °C unless otherwise noted)						
PARAMETER	SYMBOL	RMB2S	RMB4S	UNIT		
Device marking code		2R	4R			
Maximum repetitive peak reverse voltage	V <sub>RRM</sub>	200	400	V		
Maximum RMS voltage	V <sub>RMS</sub>	140	280	V		
Maximum DC blocking voltage	V <sub>DC</sub>	200	400	V		
$\begin{array}{ll} \mbox{Maximum average forward output} & \mbox{on glass-epoxy P.C.B.} \\ \mbox{rectified current at } T_{\rm A} = 30 \ {}^{\circ}{\rm C} & \mbox{on aluminum substrate} \end{array}$	I <sub>F(AV)</sub>	0.5 <sup>(1)</sup> 0.8 <sup>(2)</sup>		A		
Peak forward surge current 8.3 msec single half sine-wave superimposed on rated load	I <sub>FSM</sub>	30		A		
Rating for fusing (t < 8.3 ms)	l <sup>2</sup> t	5.0		A <sup>2</sup> s		
Operating junction and storage temperature range	T <sub>J</sub> , T <sub>STG</sub>	- 55 to + 150 °C		°C		

#### Notes:

(1) On glass epoxy P.C.B. mounted on 0.05 x 0.05" (1.3 x 1.3 mm) pads

(2) On aluminum substrate P.C.B. with an area of 0.8" x 0.8" (20 x 20 mm) mounted on 0.05 x 0.05" (1.3 x 1.3 mm) solder pad





ROHS COMPLIANT

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<b>ELECTRICAL CHARACTERISTICS</b> ( $T_A = 25 \text{ °C}$ unless otherwise noted)						
PARAMETER	TEST CONDITIONS		SYMBOL	RMB2S	RMB4S	UNIT
Maximum instantaneous forward voltage drop per diode	0.4 A V <sub>F</sub> 1.25		25	V		
Maximum DC reverse current at rated DC blocking voltage per diode		T <sub>A</sub> = 25 °C T <sub>A</sub> = 125 °C	I <sub>R</sub>	5.0 100		μΑ
Maximum reverse recovery time per diode	$I_{\rm F} = 0.5$ A, $I_{\rm R} = 1.0$ A, $I_{\rm rr} = 0.25$ A		t <sub>rr</sub>	150		ns
Typical junction capacitance per diode	4.0 V, 1 MHz		CJ	13		pF

<b>THERMAL CHARACTERISTICS</b> ( $T_A = 25 \degree C$ unless otherwise noted)				
PARAMETER	SYMBOL	RMB2S	UNIT	
Typical thermal resistance	R <sub>θJA</sub> R <sub>θJA</sub> R <sub>θJL</sub>	85 <sup>(1)</sup> 70 <sup>(2)</sup> 20 <sup>(1)</sup>		°C/W

Notes:

(1) On glass epoxy P.C.B. mounted on 0.05 x 0.05" (1.3 x 1.3 mm) pads

(2) On aluminum substrate P.C.B. with an area of 0.8" x 0.8" (20 x 20 mm) mounted on 0.05 x 0.05" (1.3 x 1.3 mm) solder pad

ORDERING INFORMATION (Example)						
PREFERRED P/N	UNIT WEIGHT (g)	PREFERRED PACKAGE CODE	BASE QUANTITY	DELIVERY MODE		
RMB4S-E3/45	0.22	45	100	Tube		
RMB4S-E3/80	0.22	80	3000	13" diameter paper tape and reel		

### **RATINGS AND CHARACTERISTICS CURVES**

(T<sub>A</sub> = 25 °C unless otherwise noted)

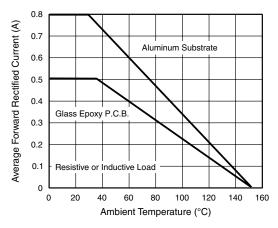
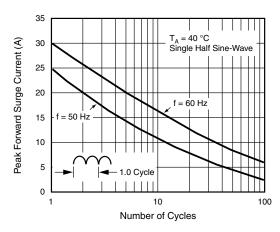
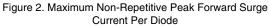


Figure 1. Maximum Forward Current Derating Curve







# **RMB2S & RMB4S**

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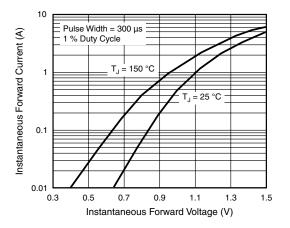


Figure 3. Typical Instantaneous Forward Characteristics Per Diode

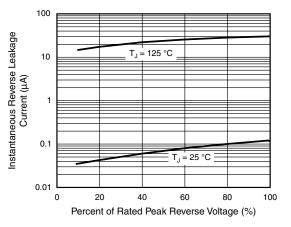
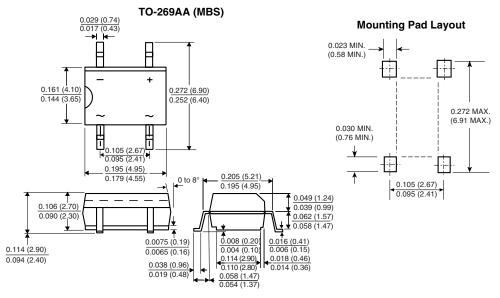


Figure 4. Typical Reverse Leakage Characteristics Per Diode

#### **PACKAGE OUTLINE DIMENSIONS** in inches (millimeters)



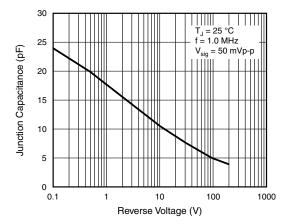


Figure 5. Typical Junction Capacitance Per Diode



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